



Product Change Notification: MFOL-300MBY736

Date:

31-Jan-2025

Product Category:

Ethernet Phys

Notification Subject:

CCB 7393 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8051, KSZ8081, and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Affected CPNs:

[**MFOL-300MBY736_Affected_CPN_01312025.pdf**](#)

[**MFOL-300MBY736_Affected_CPN_01312025.csv**](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8051, KSZ8081, and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu
Die Attach Material	3280	3280NP
Molding Compound Material	G700LTD	G700LTD
Lead frame Material	A194	A194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 04, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-300MBY736_Qual Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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